

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1951	"257"/\$.ccls. and mold with (protrus\$4 project\$4 opening cavit\$3) and (chip die ic) and (substrate board carrier) with (via hole opening)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/06 12:28
L2	279	"361"/\$.ccls. and mold with (protrus\$4 project\$4 opening cavit\$3) and (chip die ic) and (substrate board carrier) with (via hole opening)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/06 12:45
L3	834	"438"/\$.ccls. and mold with (protrus\$4 project\$4 opening cavit\$3) and (chip die ic) and (substrate board carrier) with (via hole opening)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/06 13:07
L4	398	"29"/\$.ccls. and mold with (protrus\$4 project\$4 opening cavit\$3) and (chip die ic) and (substrate board carrier) with (via hole opening)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/06 13:08